

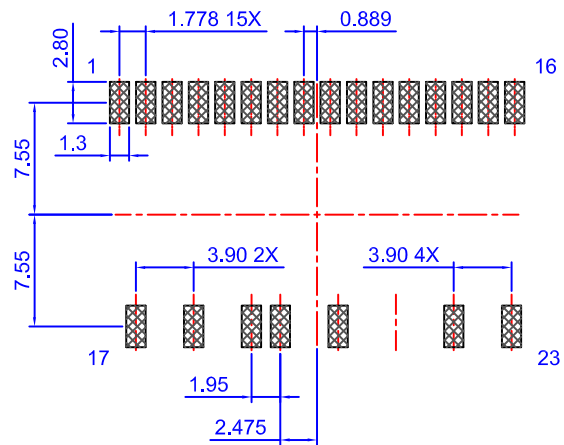
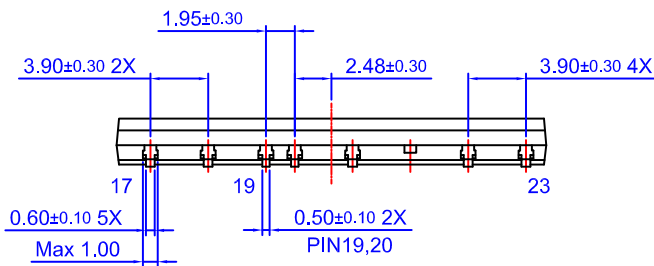
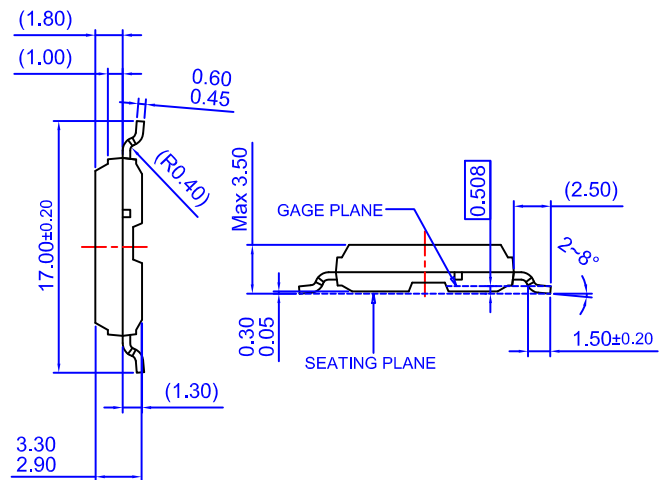
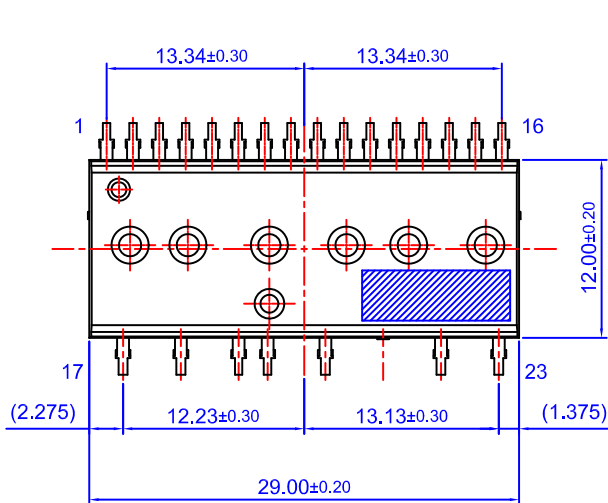
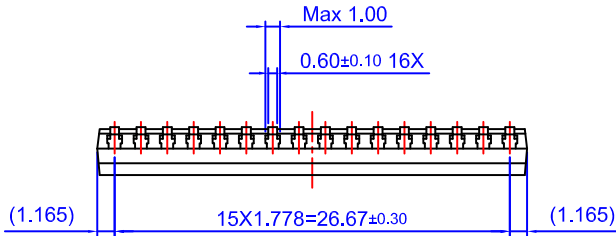
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SPM5H-023 / 23LD, PDD STD, SPM23-BD (Ver1.5) SMD TYPE CASE MODEM ISSUE O

DATE 31 JAN 2017



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPM5H-023 / 23LD, PDD STD, SPM23-BD (Ver1.5) SMD TYPE	PAGE 1 OF 2

